What is claimed is:

1. A shock-absorbing member disposed on a main body of equipment, and comprising a shock-absorbing base part and a shock-absorbing flexible part,

wherein the shock-absorbing base part has a thickness smaller than that of the shock-absorbing flexible part, and the shock-absorbing base part buckles so as to absorb a shock when receiving an impact.

2. The shock-absorbing member according to claim 1, wherein the shock-absorbing base part forms a bending part which is vertical to the shock direction, and starts buckling at the bending part of the shock-absorbing base part so as to absorb a shock when receiving an impact.

3. The shock-absorbing member according to claim 1, wherein the shock-absorbing base part and the shock-absorbing flexible part are disposed so that their long sides are substantially in parallel with a direction of an impact force.

4. The shock-absorbing member according to claim 1, wherein the shock-absorbing base part and the shock-absorbing flexible part are integrally molded forming a unit.

5. The shock-absorbing member according to claim 1 or claim 2, wherein the shock-absorbing base part is narrow in a direction of its effective width which is vertical to long side of the shock-absorbing base part.

6. The shock-absorbing member according to claim 1 or claim 2, wherein the shock-absorbing base part is thin in a direction of its effective thickness which

is vertical to long side of the shock-absorbing base part.

7. The shock-absorbing member according to claim 1, wherein the shock-absorbing base part has a hardness higher than that of the shock-absorbing flexible part.

8. An electronic device having a shock-absorbing member which is composed of a shock-absorbing base part and a shock-absorbing flexible part and is disposed outside a main body of the device,

wherein the shock-absorbing base part has a thickness smaller than that of the shock-absorbing flexible part, and the shock-absorbing base part buckles so as to absorb a shock when receiving a shock of impact.

9. The electronic device according to claim 8, wherein the shock-absorbing base part forms a bending part which is vertical to the shock direction, and starts buckling at the bending part of the shock-absorbing base part so as to absorb a shock when receiving an impact.

10. The electronic device according to claim 8, wherein a long side of the shock absorbing member composed of the shock-absorbing base part and the shock-absorbing flexible part is disposed substantially in parallel with a direction in which an impact force is applied.

11. The electronic device according to claim 9 employing the shock-absorbing member,

wherein the shock-absorbing member is formed by integrally molding the shock-absorbing base part and the shock-absorbing flexible part.

12. The electronic device according to claim 8 or claim 9 employing the shock absorbing member,

wherein the shock-absorbing base part is narrow in a direction of its effective width which is vertical to long side of the shock-absorbing base part.

13. The electronic device according to claim 8 or claim 9 employing the shock-absorbing member,

wherein the shock-absorbing base part is thin in a direction of its effective thickness which is vertical to long side of the shock-absorbing base part.

14. The electronic device according to claim 8 employing the shock-absorbing member,

wherein the shock-absorbing base part has a hardness higher than that of the shock-absorbing flexible part.

15. The electronic device according to claim 8, wherein at least 3 pieces of the shock-absorbing member are disposed between a plane of a main body of the device and a plane of an outside constituent member facing the device.

16. The electronic device according to claim 8,

wherein the shock-absorbing members are disposed between a plane of main body of the device and a plane of an outside constituent member facing the device,

wherein an angle the planes are vertically making to a joint plane between the shock-absorbing base part and the shock-absorbing flexible part of

an adjacent shock-absorbing member is 60 ° at least and 120° at most.

17. The electronic device according to one of claims of claim 8 to claim 11, and claim 13 to claim15,

wherein the shock-absorbing member is affixed to one of an outside face of the main body of the device and an inside face of the outer case.

18. The electronic device according to claim 17,

wherein the shock-absorbing member is in one of shapes of cuboid, cylinder, half-cylinder, oval-cylinder, half-oval cylinder, and polygonal prism,

wherein a face of the shock-absorbing member having the shock-absorbing base part is in parallel with the joint plane between the shock-absorbing base part and the shock-absorbing flexible part

19. The electronic device according to claim 18,

wherein the face of the shock-absorbing member having the shock-absorbing base part is at a boundary of the shock-absorbing member, and an outside peripheral diameter or an outside perimeter of the face is smaller than half an outside peripheral diameter or an outside perimeter of the shock-absorbing member.

20. A shock-absorbing method of an electronic device including a shock-absorbing member formed by integrally molding a shock-absorbing base part and the shock-absorbing flexible part,

wherein the shock-absorbing base part is thinner than the shock-absorbing flexible part, and the shock-absorbing base part buckles so as to absorb a shock when receiving an impact.

21. The shock-absorbing method according to claim 20,

wherein the shock-absorbing base part forms a bending part which is vertical to the shock direction, and starts buckling at the bending part of the shock-absorbing base part so as to absorb a shock when receiving an impact.

22. The shock-absorbing method of an electronic device according to claim 20 or claim 21,

wherein, when the shock-absorbing member absorbs the shock of the impact by buckling the shock-absorbing base part, the shock-absorbing base part bucks and absorbs the shock of the impact at an initial stage of receiving the impact, then the shock-absorbing flexible part mainly absorbs the shock.

23. The shock-absorbing method of an electronic device according to claim 18 or claim 21,

wherein the shock-absorbing members are disposed between a plane of main body of the device and a plane of an outside constituent member facing the device, so as an angle the planes vertically making to a joint plane between the shock-absorbing base part and the shock-absorbing flexible part of an adjacent shock-absorbing member becomes 60 ° at least and 120° at most.